AI Applications in Smart and Advanced Manufacturing

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Message from the Guest Editors

Smart and advanced manufacturing are transforming the global manufacturing industry. A myriad of new digital technologies are paving the way for the fourth industrial revolution that promises to make manufacturing processes more efficient, sustainable, and profitable. Products and processes become smarter and connected, providing large quantities of data. To create value from this new wealth of manufacturing and usage data, we need new, innovative tools, algorithms, and applications to process, manage, and analyze them in order to create valuable insights for manufacturers. Artificial Intelligence (AI) provides such capabilities and means to help manufacturers to gain insights to improve design, manufacturing, and handling of processes and products.

In this Special Issue of *JMMP*, we aim to report on novel applications in the field of AI applications in smart and advanced manufacturing. We are looking for original contributions for both general AI and dedicated machine learning applications to improve products and processes throughout manufacturing systems and global digital supply networks (DSN).

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Special Issue

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Message from the Editor-in-Chief

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